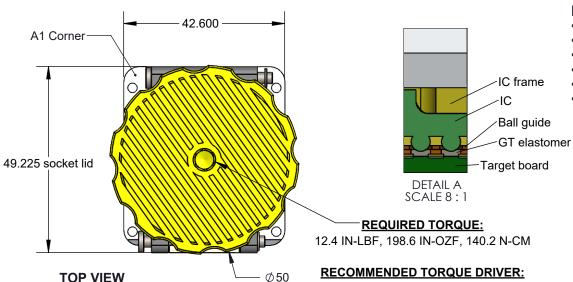
GT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS



Ø50

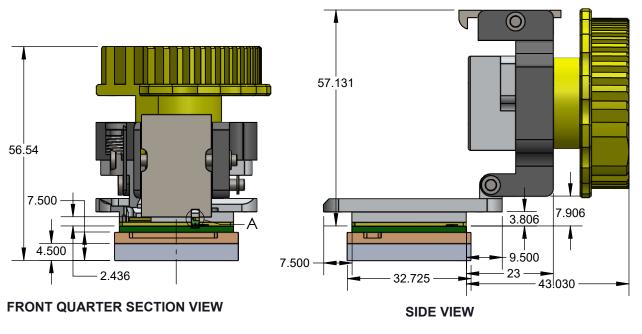
Features

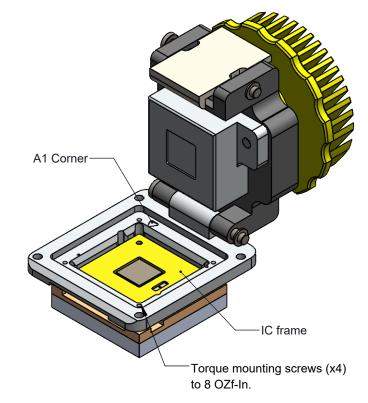
- Wide temperature range (-55C to +160C).

- Wide temperature range (-55C to +160C).
 High current capability (up to 5A).
 Excellent signal integrity at high frequencies.
 Low and stable contact resistance for reliable production yield.
 Highly compliant to accommodate wide co-planarity variations.
 Automated probe manufacturing enables low cost and short lead time.

RECOMMENDED TORQUE DRIVER:

TL-TORQUEDRIVER-13



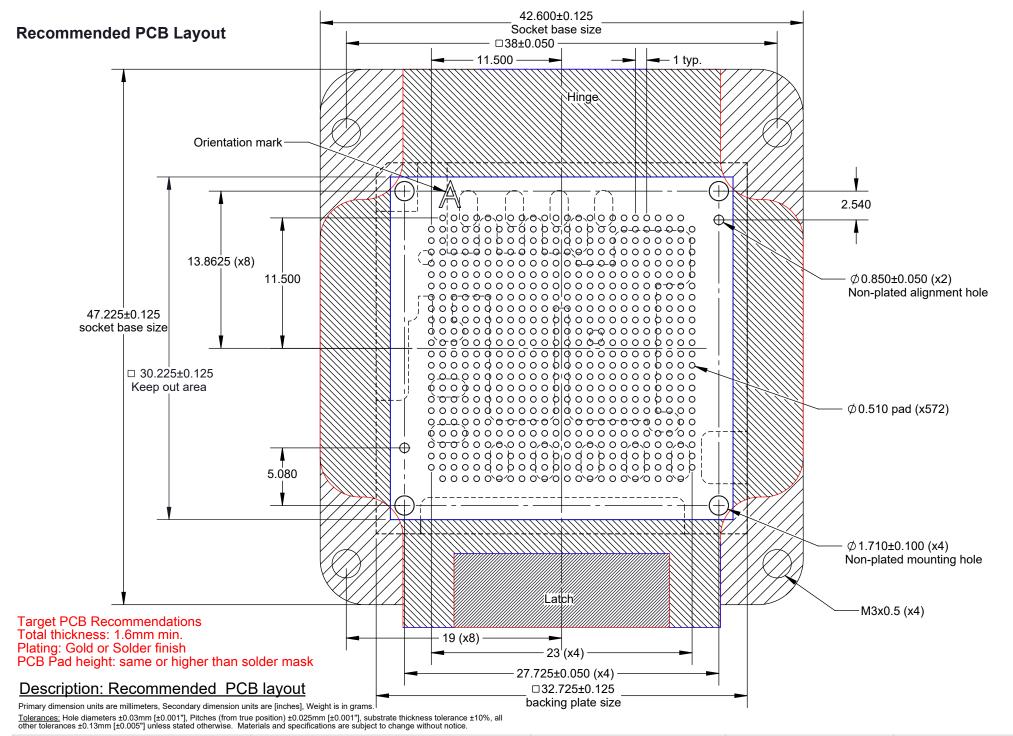


Description: Clamshell GT-BGA572 24x24 array 25x25 mm 1mm pitch

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice

GT-BGA-2019 Drawing	Material: Material <not specified=""></not>	STATUS: Released	SHEET: 1 OF 5	REV. B
Ironwood Electronics, Inc. Tele: (800) 404-0204	vveignt: 159.99	ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 1:1
www.ironwoodelectronics.com		FILE: GT-BGA-2019 Dwg	DATE: 3/20/2015	



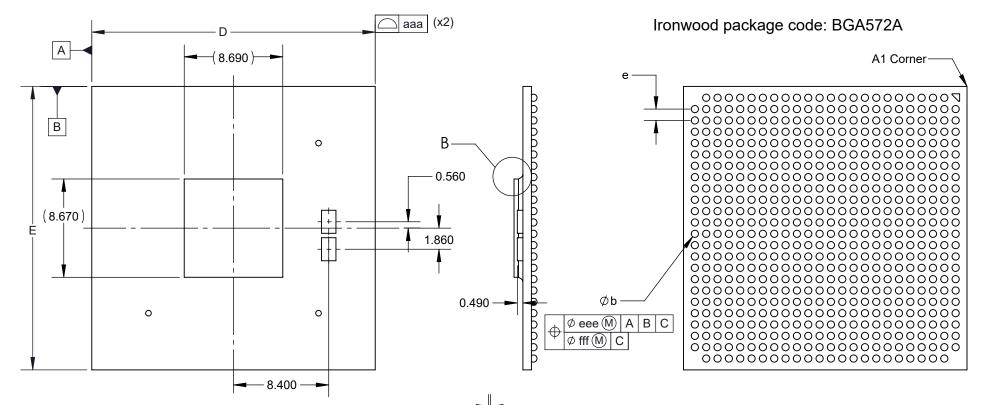
GT-BGA-2019 Drawing

Ironwood Electronics, Inc.
Tele: (800) 404-0204
www.ironwoodelectronics.com

Material: Material <not specified> Finish:

Weight: 159.99

STATUS: Released	SHEET: 2 OF 5	REV. B
ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:1
FILE: GT-BGA-2019 Dwg	DATE: 3/20/2015	



	→	
	ccc C ddd C	;
	A1 C	
DETAIL B SCALE 6:1	A3 — A2 A4 — A	

- Dimensions are in millimeters.
- 2. 3. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C.
- Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice

Weight: 159.99

STATUS: Released	SHEET: 3 OF 5	REV. B
ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 3:1
FILE: GT-BGA-2019 Dwg	DATE: 3/20/2015	

DIM

Α

Α1

A2

A3

A4 D

Ε

е

b

aaa

CCC

ddd

eee fff

MIN

1.893

0.40

0.746

1.408

24.90

24.90

0.54

0.10 Array: 24x24

NOM

2.033

0.50

0.752

0.781

1.533

25.00

25.00

1.00

0.64

0.20

0.25

0.20

0.25

MAX

2.173

0.60

__

0.816

1.658

25.10

25.10

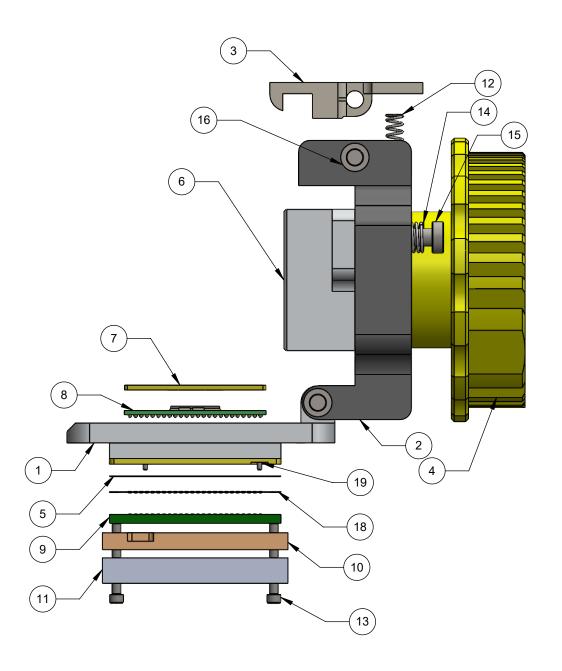
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0.74

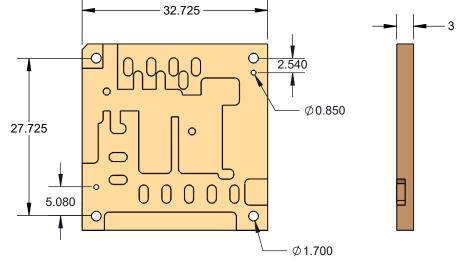
GT-BGA-2019 Drawing

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodélectronics.com

Material: Material <not specified> Finish:



ITEM NO.	DESCRIPTION	Material
1	Clamshell Socket Base 25mm IC	7075-T6 Aluminum Alloy
2	Socket Lid	7075-T6 Aluminum Alloy
3	Latch	7075-T6 Aluminum Alloy
4	Heat sink Compression Screw M24 threads	7075-T6 Aluminum Alloy
5	Ball Guide 24x24mm 1mm pitch	Kapton Polyimide/Cirlex
6	Clamshell Compression Plate for 25mm IC	7075-T6 Aluminum Alloy
7	IC frame for 25mm IC	Torlon 4203
8	BGA572 24x24 array 25x25 mm 1mm pitch	FR4 High temp
9	PCB BGA572 24x24 array 25x25 mm 1mm pitch	FR4
10	Custom Insulation Plate 25x25mm IC	Ultem 1000
11	Backing Plate 25x25mm	7075-T6 Aluminum Alloy
12	Precision Compression Spring, Zinc-Plated Music Wire, 1/2" Length, .12" OD, .016" Wire	Zinc Plated Music Wire
13	#0-80 x 0.5, SH Cap Screw	Alloy Steel
14	Spring Clamshell lid assembly	Steel Music Wire
15	Screw, M3 x 12mm, Low Head Cap, SS	18-8 Stainless Steel
16	Hinge Pin (R1774) and Snap Ring (R4681), 3mm OD, 30mm long, 1045 Stl, Blk Oxide	AISI 1045 Steel, cold drawn
17	IC Guide, 25x25mm IC, GT	Torlon 4203
18	GT Elastomer 25x25mm IC 1mm pitch 24x24 array	Conductive Elastomer
19	Dowel Pin, 1/32" 5/32" long, SS	Stainless Steel (18-8)



Description: Socket Assy

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

GT-BGA-2019 Drawing

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com Material: Material <not specified> Finish:

Weight: 159.99

STATUS: Released	SHEET: 4 OF 5	REV. B
ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 1.5:1
FILE: GT-BGA-2019 Dwg	DATE: 3/20/2015	

Insulation plate specification

Rev	Date	Initials	Description
Α	3/20/2015		Original
Updated GT to floating of Added IC guide:		SH	Updated Ball guide with floating design.

Description: Revision History

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	GT-BGA-2019 Drawing	Finish: Weight:	STATUS: Released	SHEET: 5 OF 5	REV. B
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com		ENG: S. Huang	DRAWN BY: M. Raske	SCALE: 1.5:1
			FILE: GT-BGA-2019 Dwg	DATE: 3/20/2015	